ON Semiconductor ™

Silicon PNP Power Transistors

. . . for use in power amplifier and switching circuits, — excellent safe area limits. Complement to NPN 2N5191, 2N5192

*MAXIMUM RATINGS

Rating	Symbol	2N5194	2N5195	Unit
Collector–Emitter Voltage	V_{CEO}	60	80	Vdc
Collector–Base Voltage	V_{CB}	60	80	Vdc
Emitter–Base Voltage	V_{EB}	5.0		Vdc
Collector Current	I_C	4.0		Adc
Base Current	I_B	1.0		Adc
Total Power Dissipation @ T_C = 25°C Derate above 25°C	P_D	40 320		Watts mW/°C
Operating and Storage Junction Temperature Range	T_J, T_{stg}	−65 to +150		°C/W

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Thermal Resistance, Junction to Case	θ_{JC}	3.12	°C/W
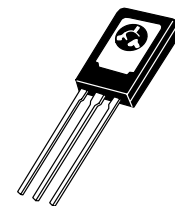
*ELECTRICAL CHARACTERISTICS (T_C = 25°C unless otherwise noted)

Characteristic		Symbol	Min	Max	Unit
OFF CHARACTERISTICS					
Collector–Emitter Sustaining Voltage (1) (I_C = 0.1 Adc, I_B = 0)	2N5194 2N5195	$V_{CEO(sus)}$	60 80	— —	Vdc
Collector Cutoff Current (V_{CE} = 60 Vdc, I_B = 0) (V_{CE} = 80 Vdc, I_B = 0)	2N5194 2N5195	I_{CEO}	— —	1.0 1.0	mAdc
Collector Cutoff Current (V_{CE} = 60 Vdc, $V_{BE(off)}$ = 1.5 Vdc) (V_{CE} = 80 Vdc, $V_{BE(off)}$ = 1.5 Vdc) (V_{CE} = 60 Vdc, $V_{BE(off)}$ = 1.5 Vdc, T_C = 125°C) (V_{CE} = 80 Vdc, $V_{BE(off)}$ = 1.5 Vdc, T_C = 125°C)	2N5194 2N5195 2N5194 2N5195	I_{CEX}	— — — —	0.1 0.1 2.0 2.0	mAdc
Collector Cutoff Current (V_{CB} = 60 Vdc, I_E = 0) (V_{CB} = 80 Vdc, I_E = 0)	2N5194 2N5195	I_{CBO}	— —	0.1 0.1	mAdc
Emitter Cutoff Current (V_{BE} = 5.0 Vdc, I_C = 0)		I_{EBO}	—	1.0	mAdc

*Indicates JEDEC Registered Data.
(1) Pulse Test: Pulse Width ≤ 300 μs, Duty Cycle ≤ 2.0%.

Preferred devices are ON Semiconductor recommended choices for future use and best overall value.

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*ELECTRICAL CHARACTERISTICS — continued (T_C = 25°C unless otherwise noted)

Characteristic		Symbol	Min	Max	Unit
ON CHARACTERISTICS					
DC Current Gain (2)		h_{FE}			—
(I_C = 1.5 Adc, V_{CE} = 2.0 Vdc)	2N5194		25	100	
	2N5195		20	80	
(I_C = 4.0 Adc, V_{CE} = 2.0 Vdc)	2N5194		10	—	
	2N5195		7.0	—	
Collector–Emitter Saturation Voltage (2)		$V_{CE(sat)}$			Vdc
(I_C = 1.5 Adc, I_B = 0.15 Adc)			—	0.6	
(I_C = 4.0 Adc, I_B = 1.0 Adc)			—	1.4	
Base–Emitter On Voltage (2)		$V_{BE(on)}$	—	1.2	Vdc
(I_C = 1.5 Adc, V_{CE} = 2.0 Vdc)					
DYNAMIC CHARACTERISTICS					
Current–Gain — Bandwidth Product		f_T	2.0	—	MHz
(I_C = 1.0 Adc, V_{CE} = 10 Vdc, f = 1.0 MHz)					

*Indicates JEDEC Registered Data.
(2) Pulse Test: Pulse Width ≤ 300 μs, Duty Cycle ≤ 2.0%.
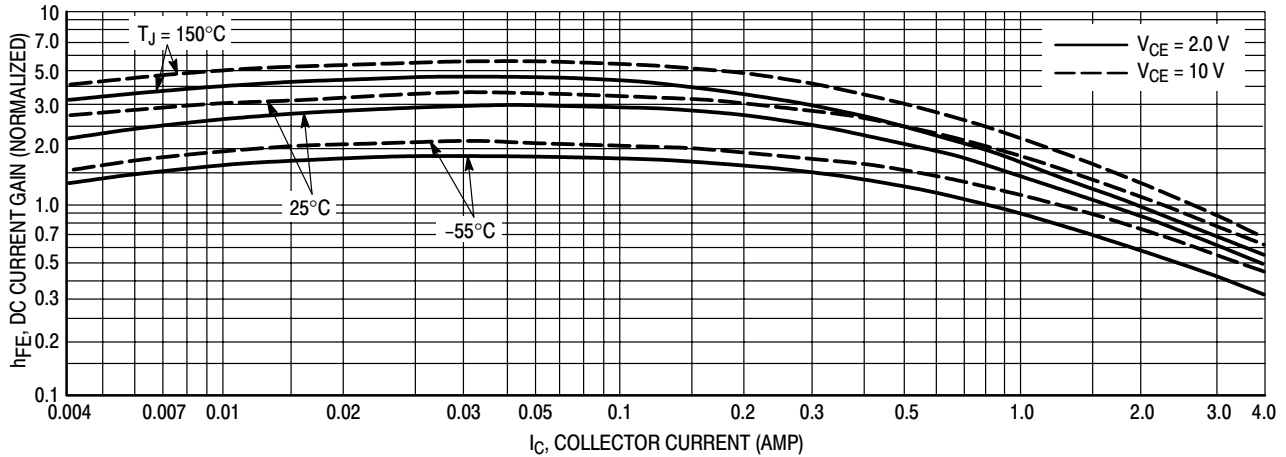
Figure 1. DC Current Gain
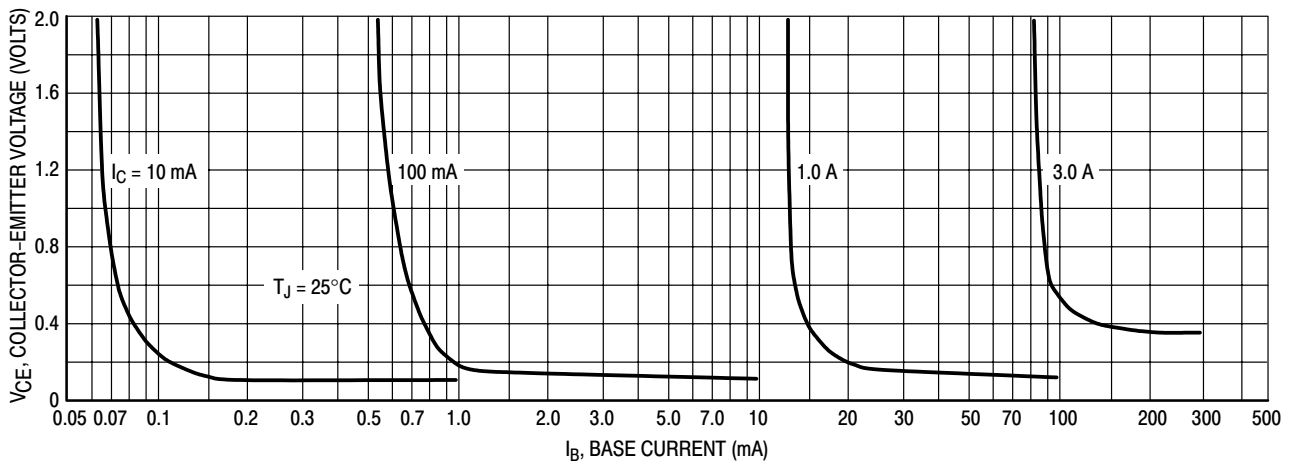
Figure 2. Collector Saturation Region
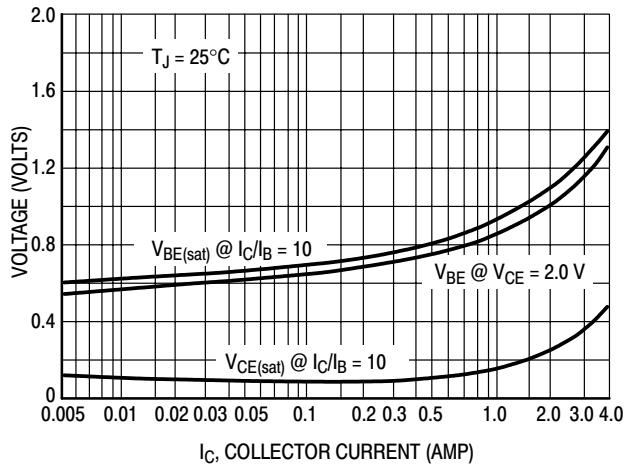
Figure 3. "On" Voltage
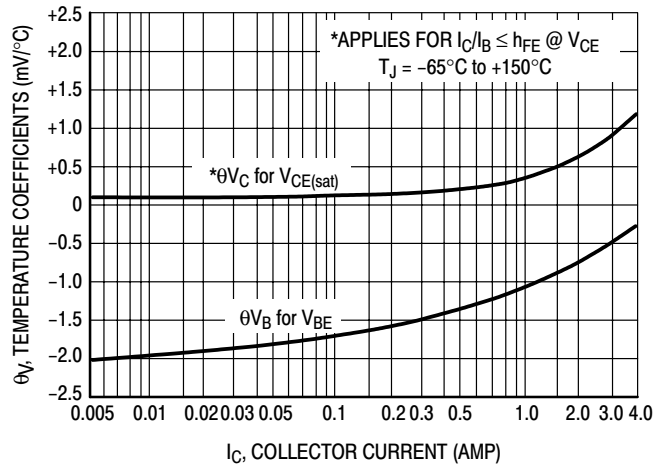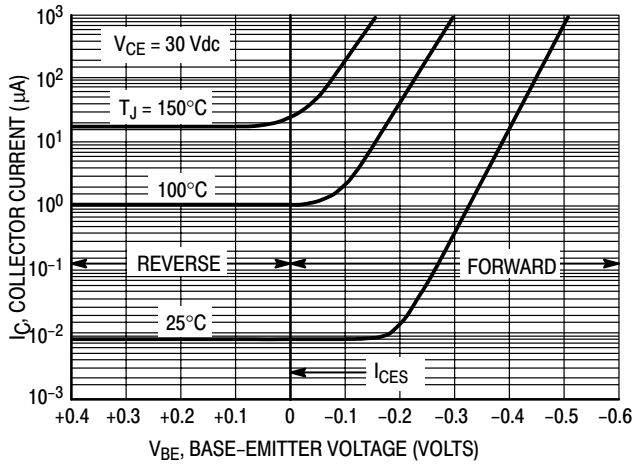

Figure 4. Temperature Coefficients
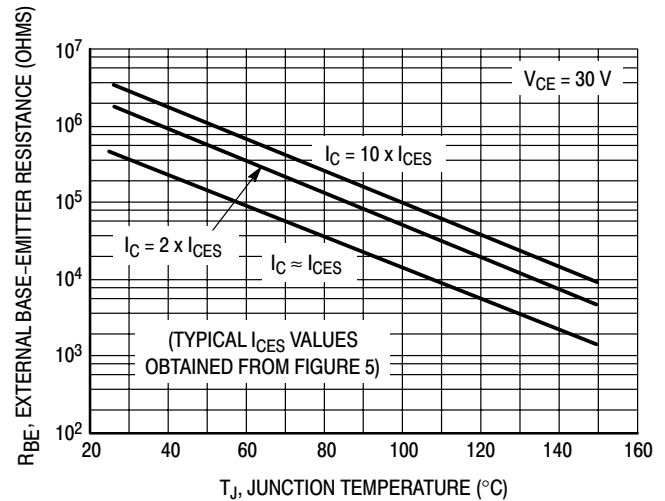

Figure 5. Collector Cut–Off Region
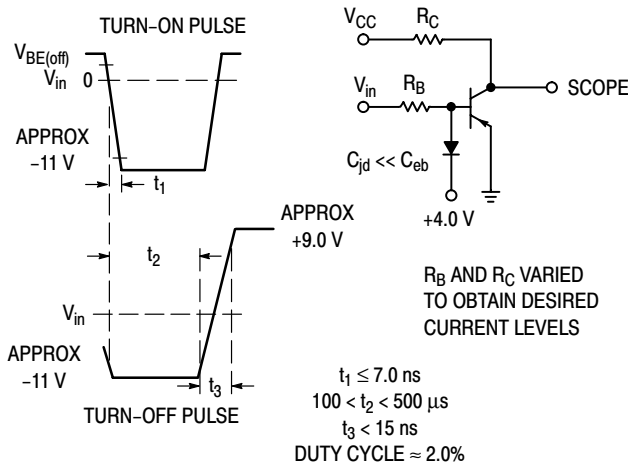

Figure 6. Effects of Base–Emitter Resistance
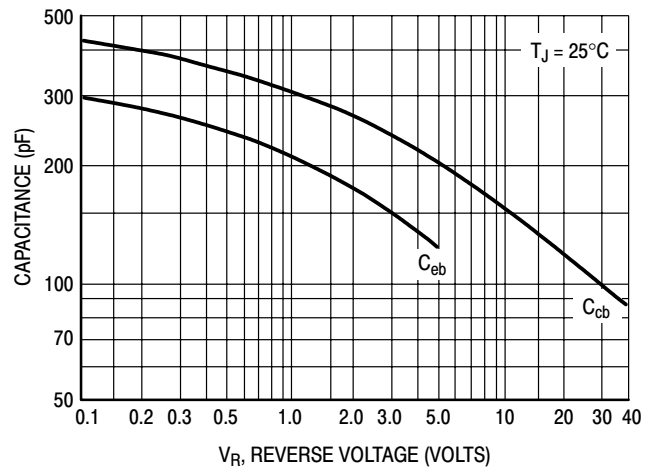

Figure 7. Switching Time Equivalent Test Circuit
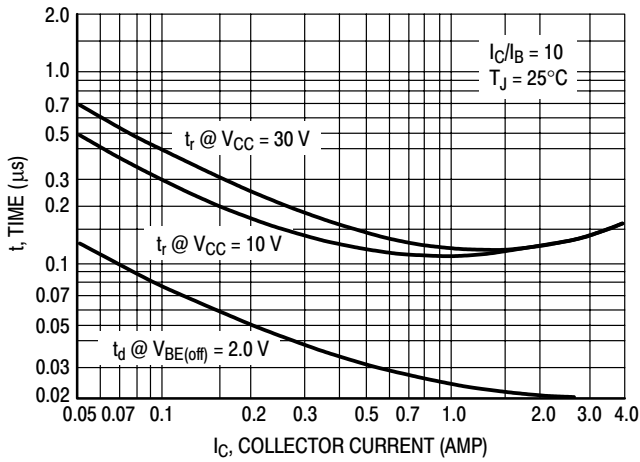

Figure 8. Capacitance
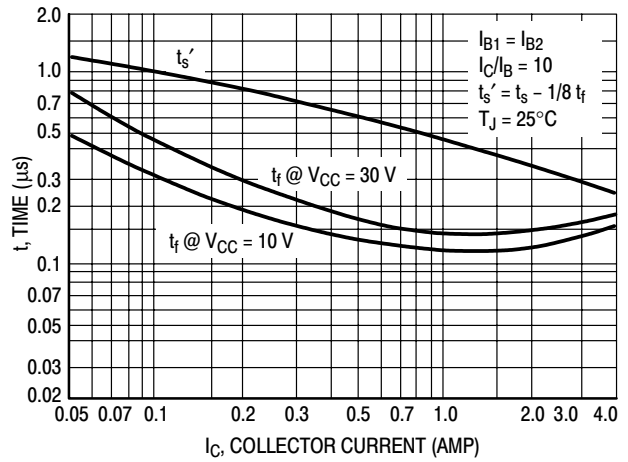
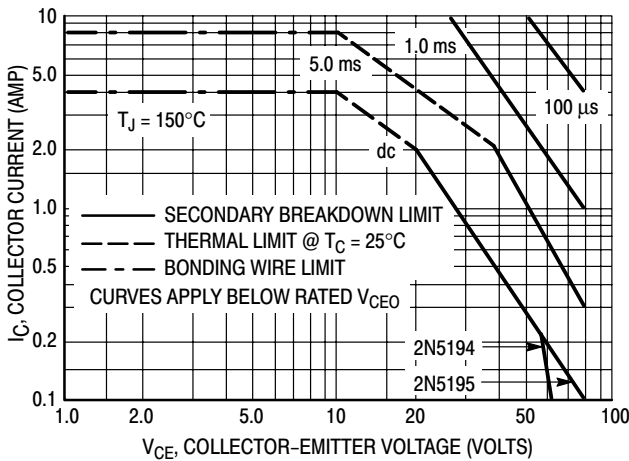**Figure 9. Turn–On Time**

Figure 10. Turn–Off Time

**Figure 11. Rating and Thermal Data
Active–Region Safe Operating Area**

Note 1:

There are two limitations on the power handling ability of a transistor; average junction temperature and second breakdown. Safe operating area curves indicate $I_C - V_{CE}$ limits of the transistor that must be observed for reliable operation; i.e., the transistor must not be subjected to greater dissipation than the curves indicate.

The data of Figure 11 is based on $T_{J(pk)} = 150°C$. T_C is variable depending on conditions. Second breakdown pulse limits are valid for duty cycles to 10% provided $T_{J(pk)} \leq 150°C$. At high–case temperatures, thermal limitations will reduce the power that can be handled to values less than the limitations imposed by second breakdown.
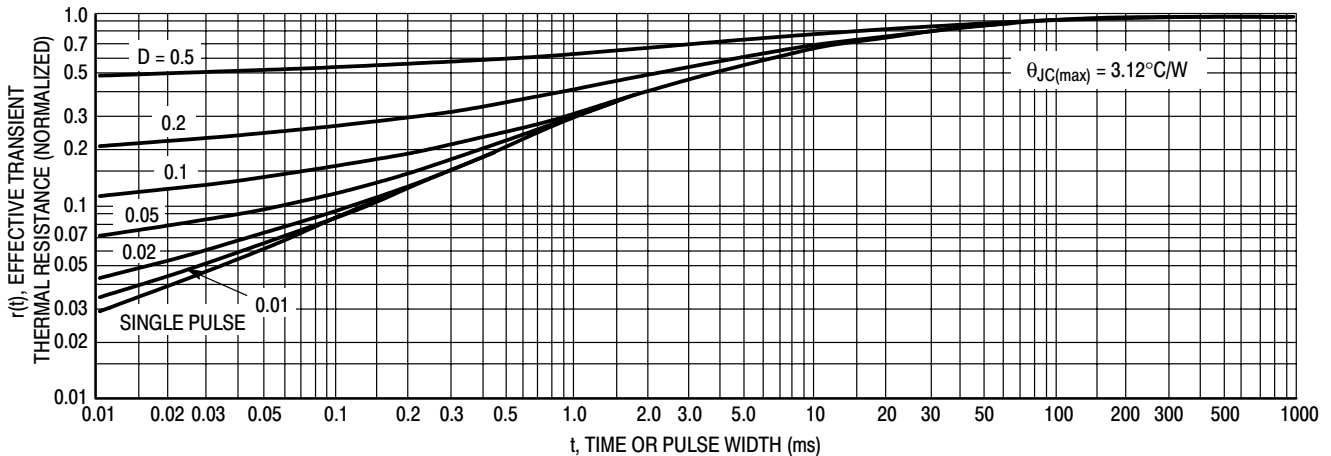
Figure 12. Thermal Response

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DESIGN NOTE: USE OF TRANSIENT THERMAL RESISTANCE DATA

$$\text{DUTY CYCLE, D} = t_1 \, f = \frac{t_1}{t_P}$$

$$\text{PEAK PULSE POWER} = P_P$$
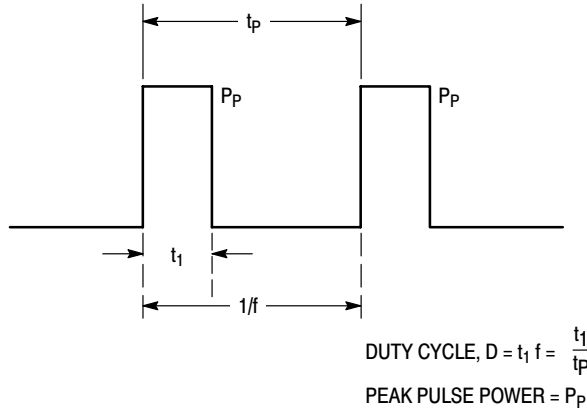
Figure 13.

A train of periodical power pulses can be represented by the model shown in Figure 13. Using the model and the device thermal response, the normalized effective transient thermal resistance of Figure 12 was calculated for various duty cycles.

To find $\theta_{JC}(t)$, multiply the value obtained from Figure 12 by the steady state value θ_{JC}.

Example:

The 2N5193 is dissipating 50 watts under the following conditions: $t_1 = 0.1$ ms, $t_p = 0.5$ ms. (D = 0.2).

Using Figure 12, at a pulse width of 0.1 ms and D = 0.2, the reading of $r(t_1, D)$ is 0.27.

The peak rise in junction temperature is therefore:

$$\Delta T = r(t) \times P_P \times \theta_{JC} = 0.27 \times 50 \times 3.12 = 42.2°C$$

PACKAGE DIMENSIONS

TO–225AA
CASE 77–09
ISSUE W
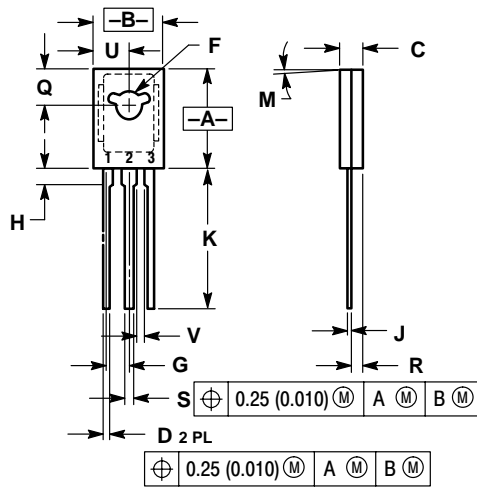
NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.425	0.435	10.80	11.04
B	0.295	0.305	7.50	7.74
C	0.095	0.105	2.42	2.66
D	0.020	0.026	0.51	0.66
F	0.115	0.130	2.93	3.30
G	0.094 BSC		2.39 BSC	
H	0.050	0.095	1.27	2.41
J	0.015	0.025	0.39	0.63
K	0.575	0.655	14.61	16.63
M	5° TYP		5° TYP	
Q	0.148	0.158	3.76	4.01
R	0.045	0.065	1.15	1.65
S	0.025	0.035	0.64	0.88
U	0.145	0.155	3.69	3.93
V	0.040	---	1.02	---

<u>Notes</u>

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